2SB0940, 2SB0940A (2SB940, 2SB940A)

Silicon PNP epitaxial planar type

For power amplification

For TV vertical deflection output

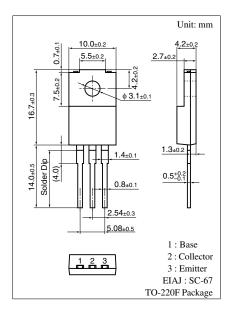
Complementary to 2SD1264 and 2SD1264A

■ Features

- \bullet High collector to emitter voltage V_{CEO}
- Large collector power dissipation P_C
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_C = 25$ °C

Parameter		Symbol	Rating	Unit
Collector to base	2SB0940	V_{CBO}	-200	V
voltage	2SB0940A		-200	
Collector to	2SB0940	V _{CEO}	-150	V
emitter voltage	2SB0940A		-180	
Emitter to base voltage		V_{EBO}	-6	V
Peak collector current		I_{CP}	-3	A
Collector current		I_C	-2	A
Collector power	$T_C = 25^{\circ}C$	P_{C}	30	W
dissipation	$T_a = 25^{\circ}C$		2	
Junction temperature		T _j	150	°C
Storage temperature		T_{stg}	-55 to +150	°C



■ Electrical Characteristics $T_C = 25$ °C

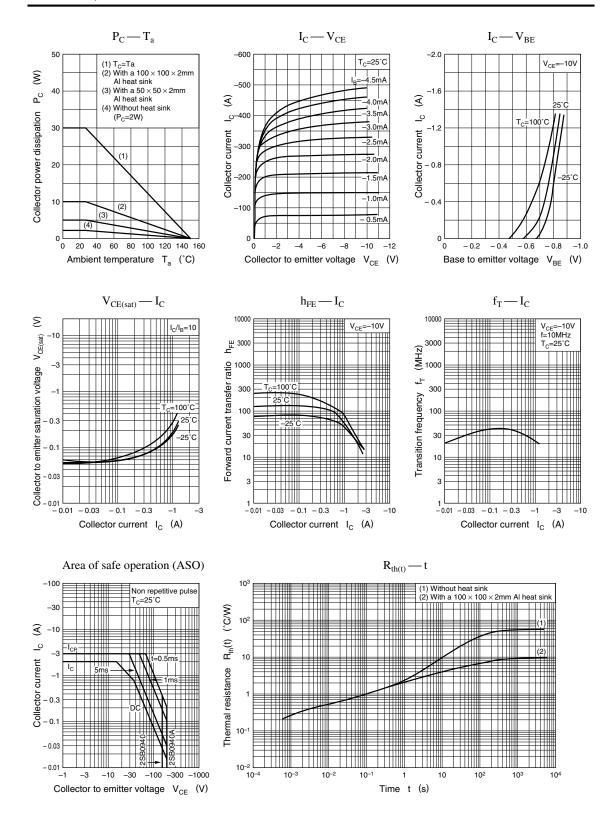
Parameter	r	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff curren	t	I_{CBO}	$V_{CB} = -200 \text{ V}, I_E = 0$			-50	μΑ
Emitter cutoff current		I_{EBO}	$V_{EB} = -4 \text{ V}, I_C = 0$			-50	μΑ
Collector to base volta	ge	V_{CBO}	$I_{\rm C} = -50 \; \mu \text{A}, I_{\rm E} = 0$	-200			V
Collector to emitter	2SB0940	V_{CEO}	$I_{\rm C} = -5 \text{ mA}, I_{\rm B} = 0$	-150			V
voltage	2SB0940A			-180			
Emitter to base voltage	;	V_{EBO}	$I_E = -500 \ \mu A, I_C = 0$	-6			V
Forward current transfe	er ratio	h _{FE1} *	$V_{CE} = -10 \text{ V}, I_{C} = -150 \text{ mA}$	60		240	
		h _{FE2}	$V_{CE} = -10 \text{ V}, I_{C} = -400 \text{ mA}$	50			
Base to emitter voltage	;	V_{BE}	$V_{CE} = -10 \text{ V}, I_{C} = -400 \text{ mA}$			-1	V
Collector to emitter satu	ration voltage	V _{CE(sat)}	$I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$			-1	V
Transition frequency		f_T	$V_{CE} = -10 \text{ V}, I_{C} = -0.5 \text{ A}, f = 10 \text{ MHz}$		30		MHz

Note) *: Rank classification

Rank	Q	Р			
h_{FE1}	60 to 140	100 to 240			

Note.) The Part numbers in the Parenthesis show conventional part number.

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